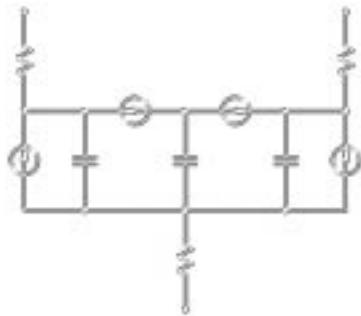


Introduction
Model Compiler
Architecture
Language
MOSFET model
Bandgap model
Flip-Flop model
Conclusions



An Extensible Compact Model Description Language and Compiler

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Model Compiler Approach

- ❑ Single description/specification of all aspects of a model
 - Topology: nodes, elements and branch voltages
 - Model identification: naming, versioning, keycodes, polarity
 - Branch voltage initialization, limiting, and collapse
 - Temperature and geometry mapping
 - Element equations
 - Model parameters
 - Simulator, solver, and extractor specifications
- ❑ Multiple targets
 - Circuit Simulators
 - Solver
 - Parameter extractor/model playback tool
 - Model documentation

Advantages of Model Compiler Approach

- ❑ Development of model can be accomplished very quickly
 - Testing ideas using solver and parameter extractor targets
 - Testing of robustness of the model in circuit simulator targets
- ❑ Error-prone model development steps are done automatically
 - Automated dependency and derivative calculations
 - Automated array indexing for parameters, inputs, outputs, intermediate calculations
 - Checking model inconsistencies
 - Correct code generation
- ❑ The resulting target need not be any less efficient than a hand-coded model
- ❑ The model description/specification is much more easily maintained than target code
- ❑ The model is self-documenting
- ❑ Once interface to a new target has been developed for one model, all other models can be retargeted

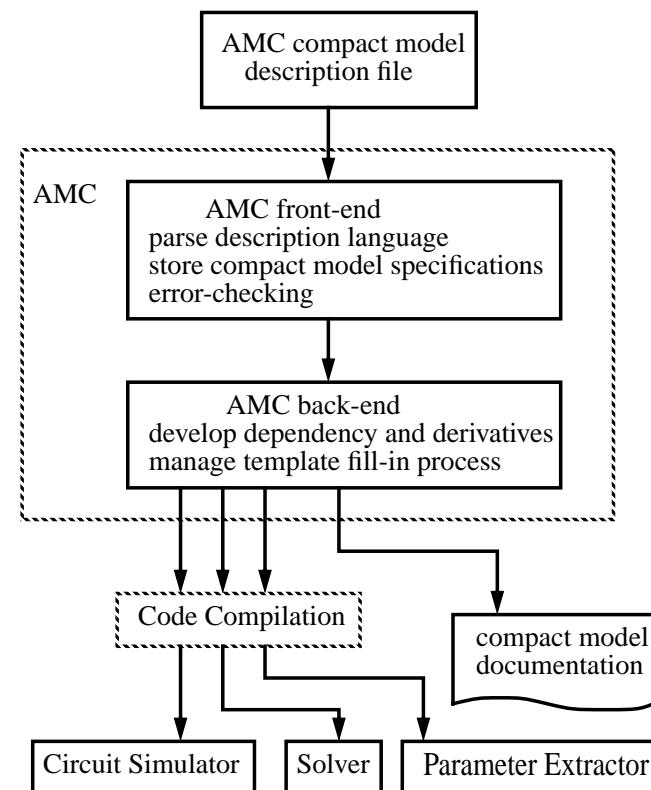


What you can do with a Model Compiler

- ❑ Compact model development
 - Solver, extractor, playback-tool
 - Check circuit simulator performance
 - Elimination of numerical problems
- ❑ Compact model support
 - Parameter extraction
 - Documentation
 - Maintain code in multiple simulators
- ❑ Support for models in new simulator
 - Write template for new simulator
 - Add target-specific code if necessary
- ❑ Consulting support
 - What-if models
 - Simplified models for documentation
 - Simulator problem debugging

Analog Model Compiler (AMC)

- ❑ Front-end: parse/store model information from description file
- ❑ Back-end: generate source-code/target-specific files



AMC

- ❑ AMC description file is an executable Tcl program
 - Each specification block corresponds to a (specification) method in the Model class
 - After model is specified (front-end), the compile procedure is called (back-end)
 - Target generation is done using template-driven process
 - Each target corresponds to a method in the Model class
- ❑ Some benefits of using Tcl/[incr Tcl]/Camelot
 - The Tcl scripting language is already well-documented
 - Model descriptions can make use of programming constructs and procedures provided by Tcl
 - Partitioning of the front-end is naturally partitioned into classes which store and provide information
 - No new parsing engine is required beyond capabilities of Tcl
 - Much error-checking is provided for free by Tcl
 - Adding new capability, checking, and targets doesn't require any compilation

Template-driven target generation

- ❑ Most of the template is usually verbatim
- ❑ Directives appear at beginning of line as “%-<word>”
 - %-IF %-ELSEIF %-ELSE %-ENDIF
 - %-TCL %-ENDTCL
- ❑ Substitution directives appear anywhere within verbatim text as “%<symbol>”
 - Replacement symbol can be established by target-specific Model code
 - Replacement symbol can be established within template %-TCL block by the “export” command
- ❑ TCL blocks
 - Symbols exported for use by following substitution directives
 - Strings output to target file using “output” command

Template example

```
#-----
# Parameter specifications
#-----
set PARA_NAMES {}
foreach spec {
    %-TCL
        set fmt "  %s %g %g %g"
        foreach name $pinp_pars {
            set nom [$PAROBJ lookup $name nominal]
            set min [$PAROBJ lookup $name minimum]
            set max [$PAROBJ lookup $name maximum]
            output [format $fmt $name $nom $min $max]
        }
    %-ENDTCL
} {
    lappend PARA_NAMES [set name [lindex $spec [set i 0]]]
    set PARA_RANG($name) [lrange $spec [incr i] end]
}
```

AMC

- ❑ Targets
 - Celerity
 - ADVICE
 - Spectre
 - VHDL-AMS
 - Verilog-AMS
 - input decks for Celerity and ADVICE
 - Solver
 - Parameter extractor
 - HTML documentation
- ❑ Code size
 - Library: 6000 lines
 - Templates: 12000 lines

AMC model description language

Specification	Description
componentSpecs	model family/component/member aspects
nodeSpecs	nodes in the equivalent circuit
branchSpecs	branches in the equivalent circuit
elementSpecs	elements in the equivalent circuit
branchInit	branch initialization
branchLimit	branch limiting
branchCollapse	branch collapse conditions
temperatureEqns	temperature-mapping equations
geometryEqns	geometry-mapping equations
elementEqns	element/noise/ac equations
parameterSpecs	model parameters
simulatorSpecs	simulator-specific configuration
solverSpecs	solver-specific configuration
extractorSpecs	extractor-specific configuration
simulatorOutput	simulator output report format
extractorData	extractor data format and screening
extractorFrame	extraction frames
verbatimLines	pass-through code

MOSFET model - 1

```

compact-model ymos {
    componentSpecs {family mosfet component ymos version 1.0}
    nodeSpecs external {d "Drain"; g "Gate"; s "Source"; b "Bulk"}
    branchSpecs {
        Vds d s "Drain to source voltage"
        Vgs g s "Gate to source voltage"
        Vbs b s "Bulk to source voltage"
    }
    elementSpecs {Ids d s}
    elementEqns Ids {
        rev = ISLTZ(Vds)
        rsp = sqrt(PHI-MIN(Vbs-Vds*rev,0))
        abc = 1+GAMMA/(2*rsp)
        Vsth = SST/1151
        Vgse = Vgs-VTH-GAMMA*(rsp-sqrt(PHI))+(ETA-(1+2*ETA)*rev)*Vds
        Vgsl = Vsth*log(1+exp(Vgse/Vsth))
        Vdss = Vgsl/(abc+THETAC*Vgsl/2)
        Vdsl = MAX(MIN(Vds,Vdss),-Vdss)
        vmob = 1+THETAS*(Vgsl+2*GAMMA*rsp)
        hmob = 1+THETAC*ABS(Vdsl)
        cls = 1+LAMBDA*ABS(Vds-Vdsl)
        Ids = BETA*cls/(vmob*hmob)*(Vgsl-abc*ABS(Vdsl)/2)*Vds
    }
    parameterSpecs instance {
        {BETA 1e-3 1e-4 0.1 A/V^2 "transconductance parameter"}
        {VTH 0.5 0.2 2.0 V "threshold voltage at Vbs=0"}
        {PHI 0.7 0.5 1.2 V "strong-inversion surface potential"}
        {GAMMA 0.7 0 2 sqrt(V) "body-effect parameter"}
        {LAMBDA 0.01 0 0.5 1/V "output-conductance parameter"}
        {THETAS 0.01 0 5 1/V "verti. field mobility parameter"}
        {THETAC 0.10 0 5 1/V "horiz. field mobility parameter"}
        {ETA 0 0 0.2 # "dibl parameter"}
        {SST 80 20 200 mV/dec "subthreshold slope"}
    }
}

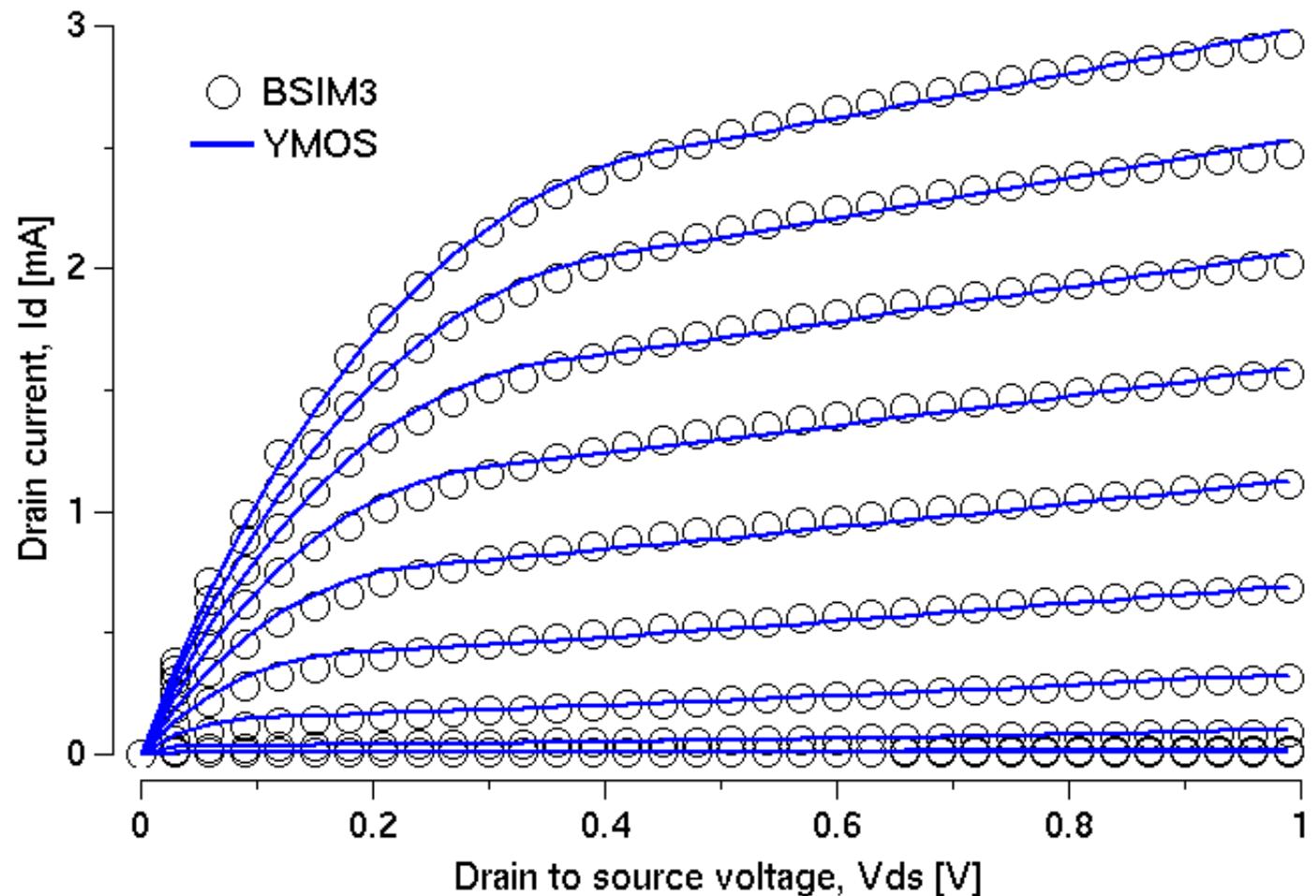
```

MOSFET model - 2

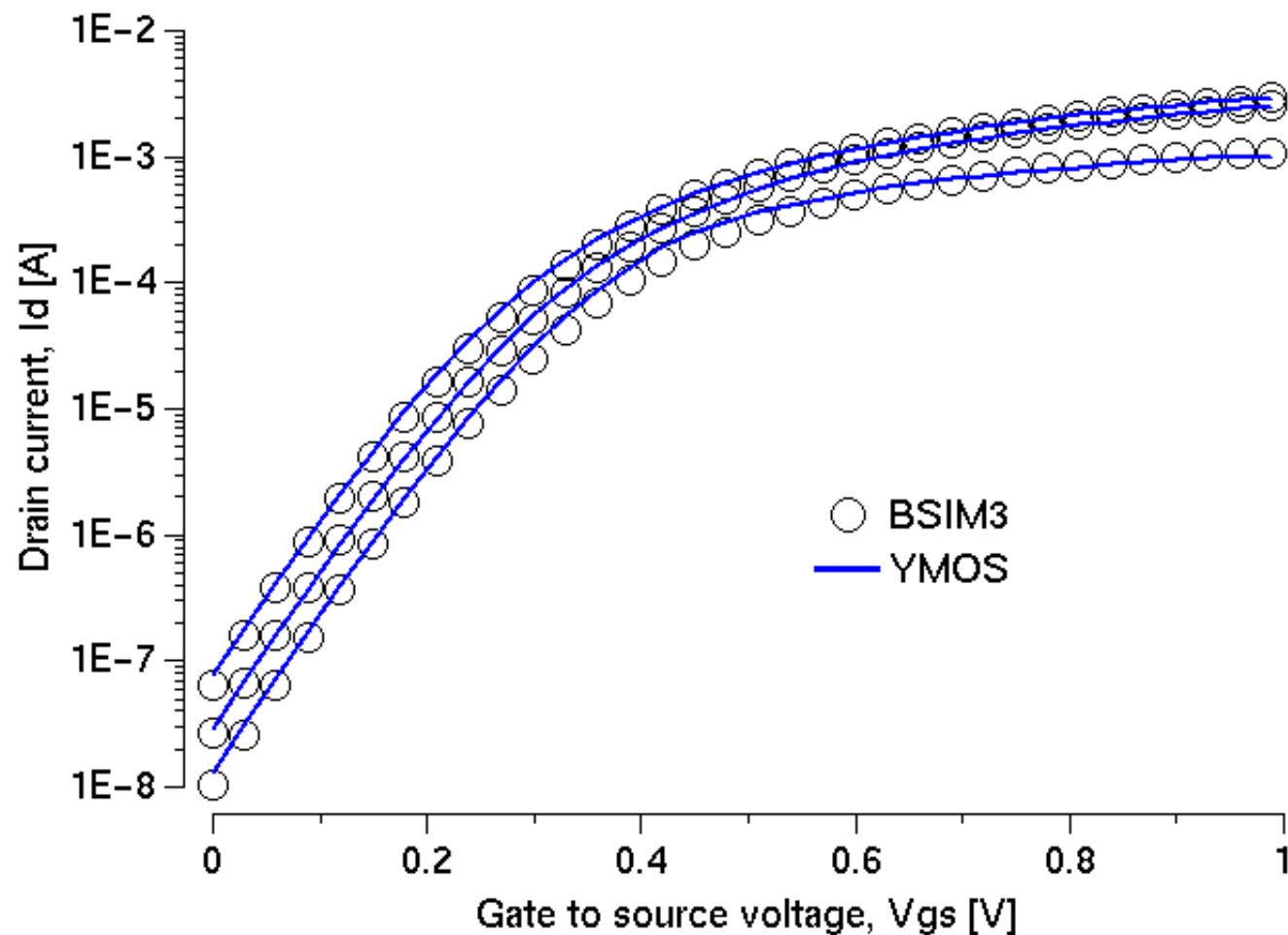
```
extractorData ts {
    interface {MODEL = Id*1E6}
    screen    {MEAST = Id*1E6}
    plots     {xy Vd MEAST MODEL -xtitle Vds -ytitle Id}
}
extractorFrame TS {
    fit      {ts}
    evaluate {ts th st}
    residual {conductance}
    include  {LAMBDA THETAC}
}
eval amc-compile $argv
exit 0
```

- ❑ No temperature or geometry model
- ❑ YMOS is symmetric about drain and source
- ❑ YMOS can be used as a “documentation” model
- ❑ Fit YMOS to simulations using Foundry-supplied BSIM3 models for 1.0V n-channel 0.13µm channel-length MOSFET from TSMC CL013LV process

YMOS output characteristics



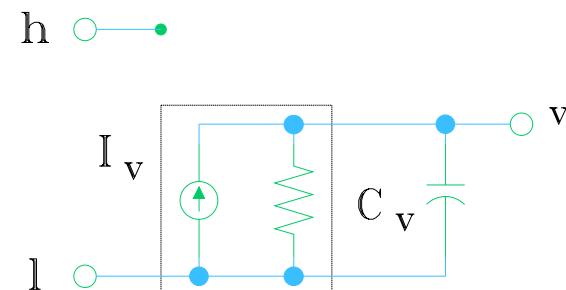
YMOS subthreshold characteristics



Bandgap reference circuit compact model - 1

```

Macro ISGT {X Y} {
    ISGT = 0.5*(1-signum(Y-X))
}
Constant Tabs 273.16
compact-model bg {
    componentSpecs {
        family bg
        component bg
        version 1.0
    }
    nodeSpecs external {
        v "bandgap reference voltage"
        h "high reference"
        l "low reference"
    }
    branchSpecs {
        Vsup h l
        Vv v l
        Vq v h
    }
    elementSpecs {
        Iv v l
        Qv v h
    }
}
```



Bandgap reference circuit compact model - 2

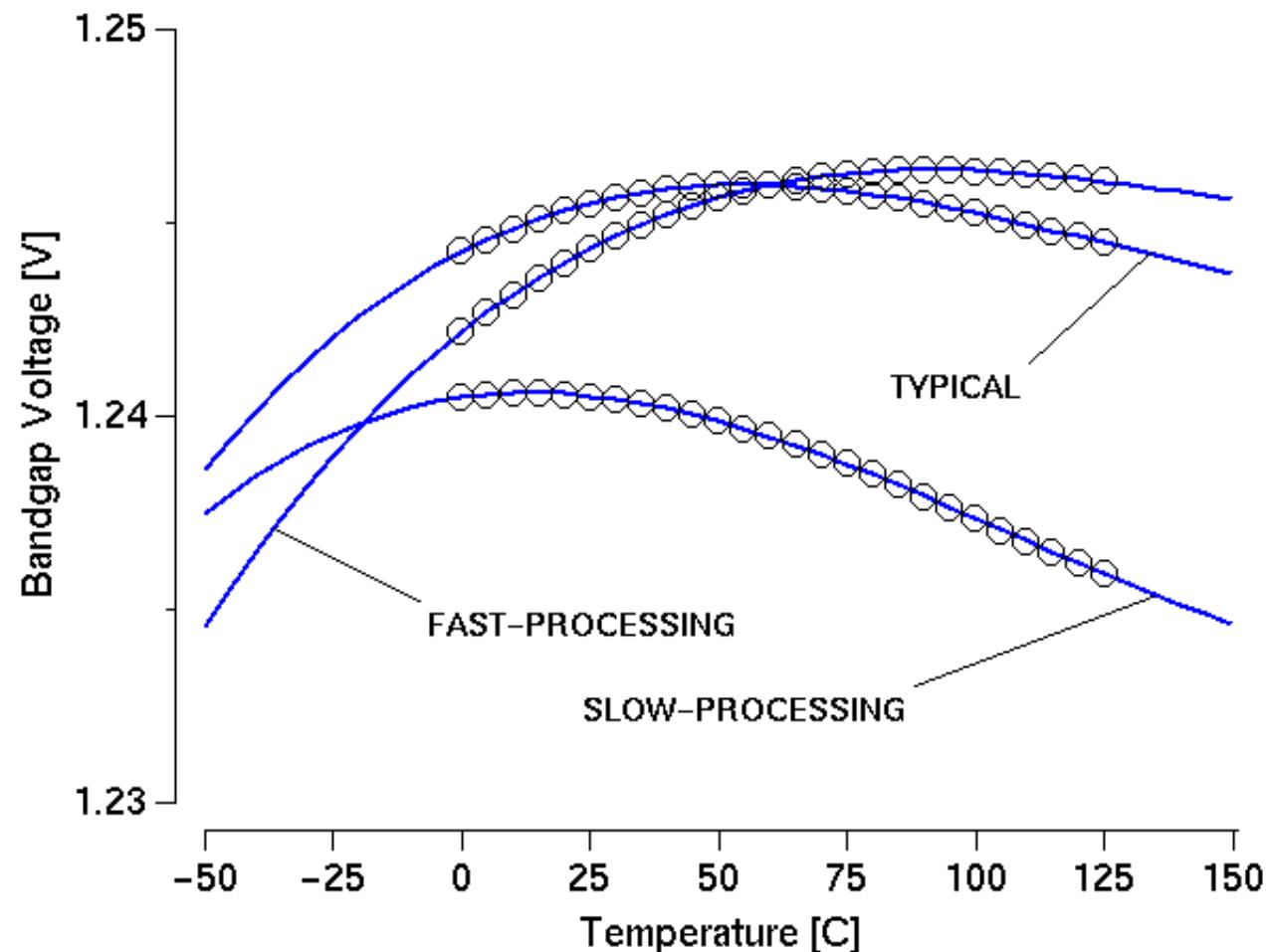
```

parameterSpecs process {
    {VF 1.2 0.5 2      V   "flat voltage"}
    {TF 65  -50 125   C   "flat temperature"}
    {A1 0   -20 20     #   "temperature coefficient 1"}
    {A2 50  0   200    #   "temperature coefficient 2"}
    {A3 50  0   200    #   "temperature coefficient 3"}
    {VDO 2.0 0   20     V   "drop-out voltage"}
}
parameterSpecs temperature_derived {VREF}
temperatureEqns {
    tn = (TEMPERATURE-TF)/(TF+Tabs)
    VREF = VF*(1+le-3*(A1+(-A2+A3*tn)*tn)*tn)
}
elementEqns Iv {Iv = Vv-VREF*ISGT(Vsup,VDO)}
elementEqns Qv {Qv = Vq*le-13}
}

eval amc-compile $argv
exit 0

```

BG model temperature characteristics



Flip-flop compact model - 1

```

Macro Dig {v vdd} {
    b = v-vdd*0.5
    s = signum(b)
    u = exp(-460.5*s*b)
    Dig = 0.5*(1+s*(1-u)/(1+u))
}
Constant Glow 1e-8

compact-model ff {
    componentSpecs {
        family ff
        component ff
        version 1.0
    }
    nodeSpecs external {
        c "clock"
        d "data"
        r "reset"
        q "noninverted output"
        b "inverted output"
        h "high reference"
        l "low reference"
    }
    nodeSpecs internal {
        m "master output"
        s "slave output"
    }
}

branchSpecs {
    Vsup h l
    Vc c l
    Vd d l
    Vr r l
    Vm m l
    Vs s l
    Vqu q h
    Vqd q l
    Vbu b h
    Vbd b l
}

elementSpecs {
    Im m l
    Is s l
    Iqu q h
    Iqd q l
    Ibu b h
    Ibd b l
    Qm m l
    Qs s l
    Qc c l
    Qd d l
    Qr r l
}

```

Flip-flop compact model - 2

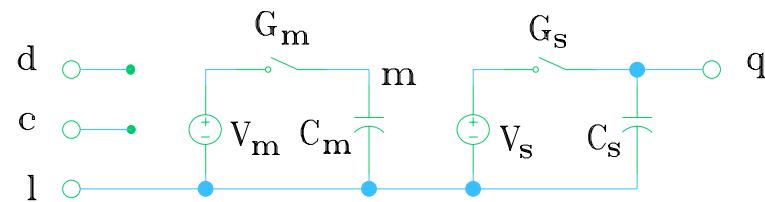
```

parameterSpecs instance {
    {DELAY      1e-9  1e-12 100      s      "clock to Q delay"}
    {CIN       1e-14  0        1e-9      F      "input capacitance"}
}
elementEqns Im {
    chi = Dig(Vc,Vsup)
    rhi = Dig(Vr,Vsup)
    gr = rhi+(1-rhi)*Glow
    Im = (chi+(1-chi)*Glow)*(Vm-Vsup*Dig(Vd,Vsup)) + gr*Vm
}
elementEqns Is {
    Is = ((1-chi)+chi*Glow)*(Vs-Vsup*Dig(Vm,Vsup)) + gr*Vs
}
elementEqns Iqu {
    shi = Dig(Vs,Vsup)
    gq = shi+(1-shi)*Glow
    gb = (1-shi)+shi*Glow
    Iqu = gq*Vqu
}
elementEqns Iqd {Iqd = gb*Vqd}
elementEqns Ibu {Ibu = gb*Vbu}
elementEqns Ibd {Ibd = gq*Vbd}
elementEqns Qm {Qm = DELAY*1.5*Vm}
elementEqns Qs {Qs = DELAY*1.5*Vs}
elementEqns Qc {Qc = CIN*Vc}
elementEqns Qd {Qd = CIN*Vd}
elementEqns Qr {Qr = CIN*Vr}
}

eval amc-compile $argv
exit 0

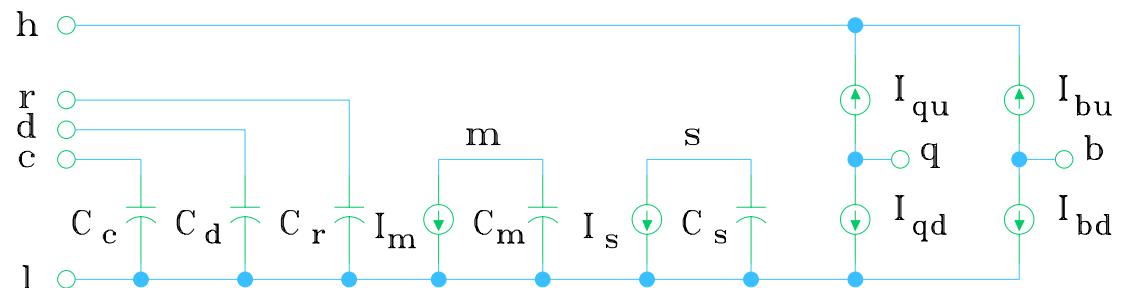
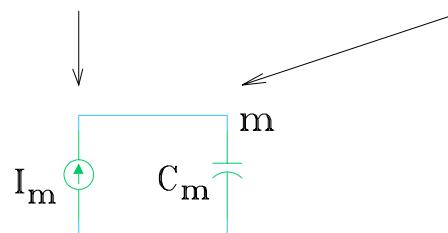
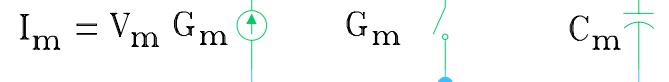
```

FF model formulation

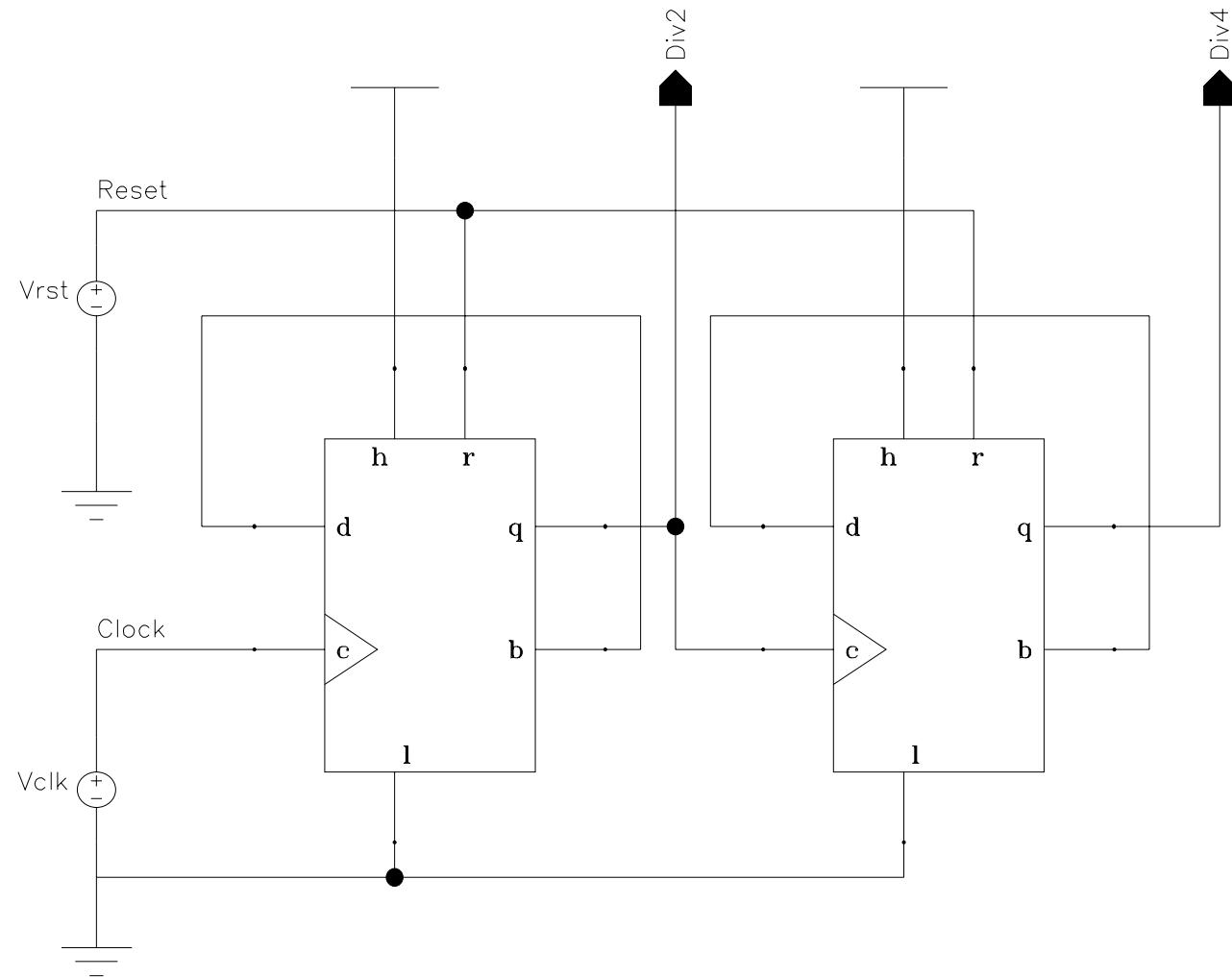


$$V_m = V_{sup} \operatorname{Dig}(V(d))$$

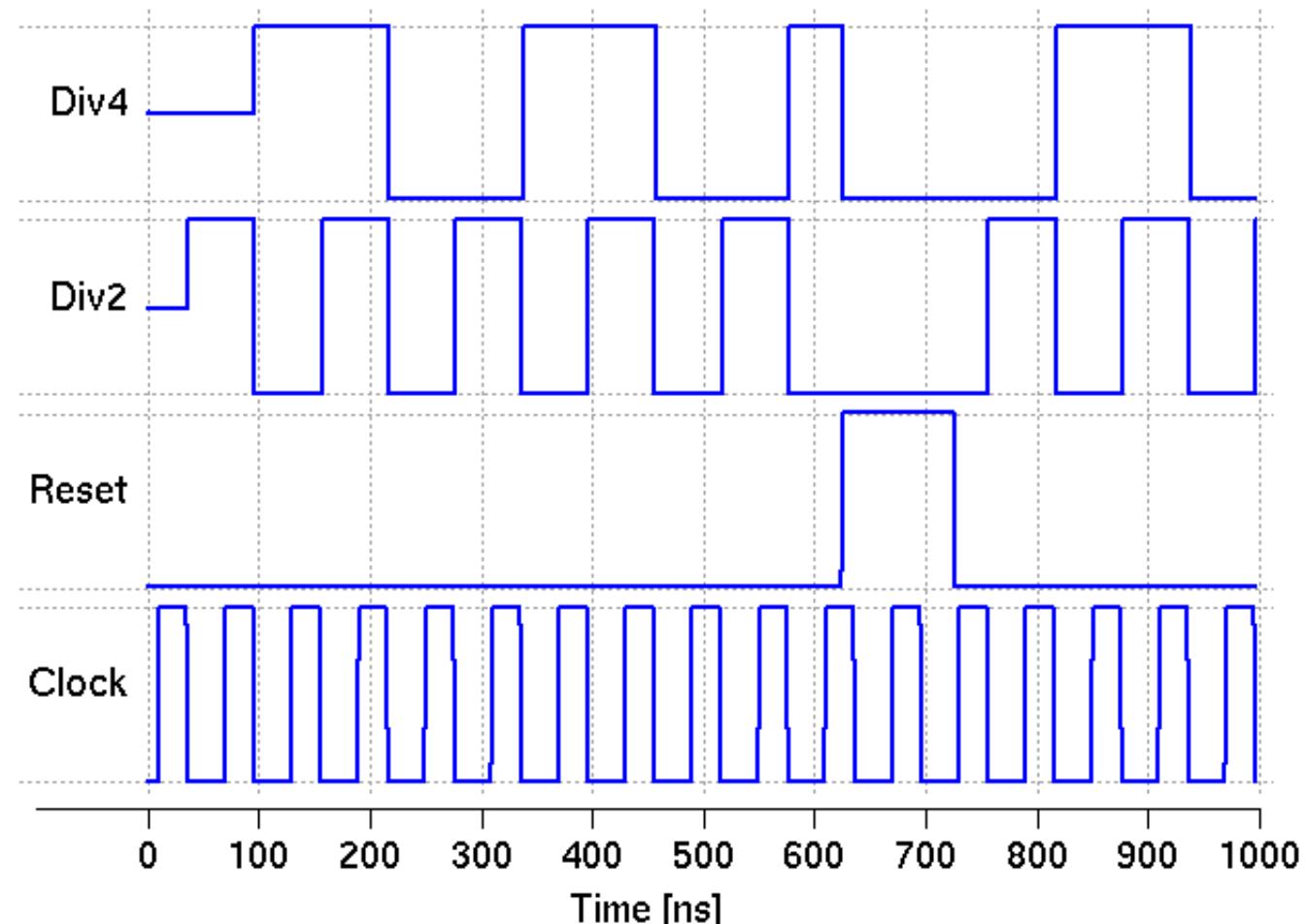
$$G_m = 1.0 \operatorname{Dig}(V(c))$$



Ripple-counter using FF model



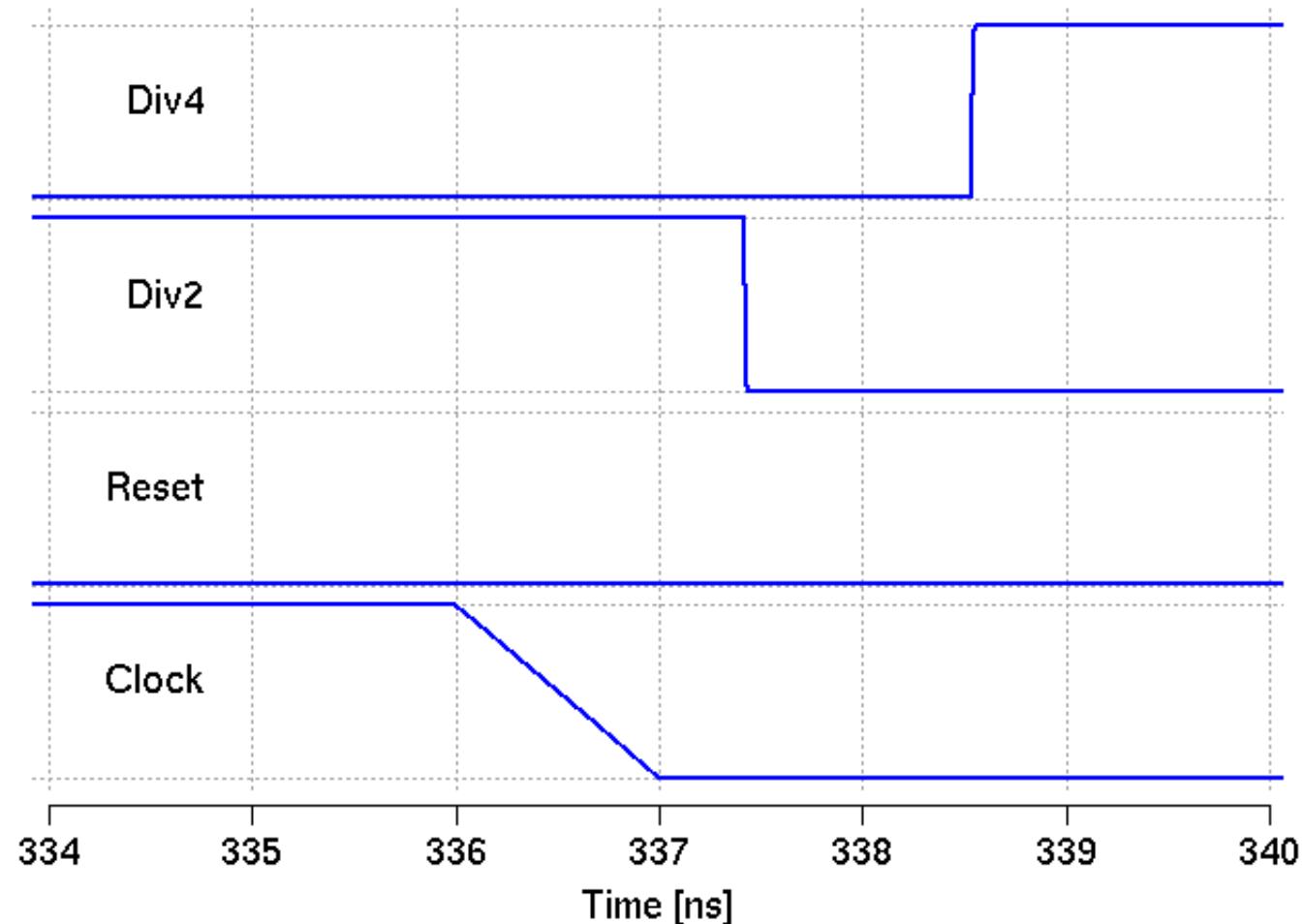
Ripple-counter output signals - 1



- Introduction
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- Flip-Flop model
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Ripple-counter output signals - 2



Conclusions

- ❑ Model compiler technology has long been successfully used for device compact model development and support at AT&T, Lucent, Agere
- ❑ AMC can also be used for high-level circuit modules
- ❑ AMC for model development, model support, model porting, consulting support:
 - Fewer resources are required for development, maintenance, support, consulting
 - Only a single source must be maintained
 - Development is rapid and correct by construction
 - Support for other simulators can be accomplished quickly
- ❑ AMC approach - Tcl/Tk, [incr Tcl], templates - greatly improves the maintainability of the compiler itself

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